Surface Mount Multilayer Ceramic Capacitors (SMD MLCCs) for High Power Applications

Ultra HiQ-CBR Squared Series, COG Dielectric, Low ESR 250 VDC, 1 MHz - 50 GHz (RF & Microwave)



Overview

KEMET's Ultra HiQ-CBR 0505 Series surface mount multilayer ceramic capacitors (MLCCs) in C0G dielectric feature a robust and exceptionally stable copper electrode dielectric system as well as a square case size that offers excellent low loss performance (ultra high Q). These devices provide extremely low ESR and high self-resonance characteristics, and are well-suited for higher power applications where minimal heating due to I²R losses are a factor. CBR Series capacitors exhibit no change in capacitance with respect to time and voltage, and boast a negligible change in capacitance with reference to ambient



temperature. Capacitance change is limited to ±30 ppm/°C from -55°C to +125°C.

CBR Series devices are suitable for many circuit applications including RF power amplifiers, mixers, oscillators, low noise amplifiers, filter networks, antenna tuning, timing circuits, delay lines, and MRI imaging coils.

Benefits

- · Ultra high Q and extremely low ESR
- 0505 Square case size for higher SRF versus standard EIA case sizes
- · High thermal stability
- 1 MHz to 50 GHz frequency range
- Operating temperature range of -55°C to +125°C
- Base metal electrode (BME) dielectric system
- Pb-free and RoHS compliant
- · DC voltage rating of 250 V
- Capacitance offerings ranging from 0.4 pF up to 100 pF
- Available capacitance tolerances of ±0.05 pF, ±0.1 pF, ±0.25 pF, ±0.5 pF, ±1%, ±2%, and ±5%



Ordering Information

CBR	05	C	330	F	Α	G	A	С	
Series	Case Size (L"x W")	Specification/ Series	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Dielectric	Termination Style	Termination Finish	Packaging/ Grade (C-Spec) ¹
CBR	05 = 0505	C = Standard	Two significant digits and number of zeros Use 9 for 1.0 – 9.9 pF Use 8 for 0.1 – 0.99 pF e.g., 2.2 pF = 229 e.g., 0.5 pF = 508	A = ±0.05 pF B = ±0.10 pF C = ±0.25 pF D = ±0.50 pF F = ±1% G = ±2% J = ±5%	A = 250 V	G = COG	A = N/A	C = 100% Matte Sn	Blank = 7" Reel Unmarked

¹ When ordering CBR Series devices, a "suffix" or "C-Spec" is not required to indicate a 7" reel packaging option. CBR devices are only available and shipped on 7" reels (paper tape). Bulk bag and cassette packaging options are not available. Please contact KEMET if you have a specific, non-standard packaging requirement.



Benefits cont'd

- No piezoelectric noise
- No capacitance change with respect to applied rated DC voltage
- Negligible capacitance change with respect to temperature
- · No capacitance decay with time
- · Non-polar device, minimizing installation concerns
- 100% pure matte tin-plated termination finish allowing for excellent solderability

Applications

Typical applications include critical timing, tuning, bypass, coupling, feedback, filtering, impedance matching and DC blocking.

Field applications include wireless and cellular base stations, wireless LAN, subscriber-based wireless services, wireless broadcast equipment, satellite communications, RF power amplifier (PA) modules, filters, voltage-controlled oscillators (VCOs), PAs, matching networks, RF modules, satellite communications and medical electronics.

Qualification

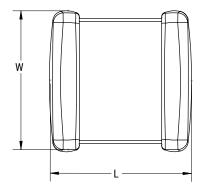
RF and microwave products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 4, Performance & Reliability.

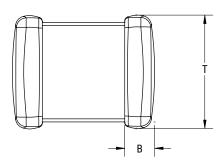
Environmental Compliance

Pb-free and RoHS compliant.



Dimensions - Millimeters (Inches)





Case Size (in.)	Case Size (mm)	L Length	W Width	T Thickness	B Bandwidth	Mounting Technique
0505	1414	1.40+0.38/-0.25 (0.055+0.015/-0.01)	1.40±0.38 (0.055±0.015)	1.15±0.15 (0.045±0.006)	0.25+0.25-0.13 (0.010+0.010-0.005)	Solder Reflow Only

Electrical Parameters/Characteristics

Item	Parameters/Characteristics
Operating Temperature Range:	-55°C to +125°C
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	0 ±30 ppm/°C
Aging Rate (Maximum % Capacitance Loss/Decade Hour):	0%
¹ Dielectric Withstanding Voltage (DWV):	See Dielectric Withstanding Voltage Table (5±1 seconds and charge/discharge not exceeding 50 mA)
² Quality Factor (Q):	≥ 1,400 for capacitance values ≥30 pF ≥ 800 + 20°C for capacitance values < 30 pF
³ Insulation Resistance (IR) Limit at 25°C:	10 GΩ minimum (rated voltage applied for 120±5 seconds)

¹ DWV is the voltage a capacitor can withstand (survive) for a short period of time. It exceeds the nominal and continuous working voltage of the capacitor.

 $^{^2}$ Capacitance and quality factor (Q) measured at 1 MHz \pm 100 kHz and 1.0 \pm 0.2 Vrms.

 $^{^3}$ To obtain IR limit, divide M Ω - μ F value by the capacitance and compare to G Ω limit. Select the lower of the two limits. Note: When measuring capacitance it is important to ensure the set voltage level is held constant. The HP4284 and Agilent E4980 have a feature known as Automatic Level Control (ALC). The ALC feature should be switched to "ON."

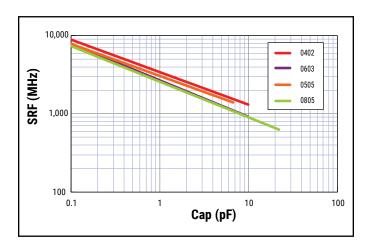


Dielectric Withstanding Voltage Table

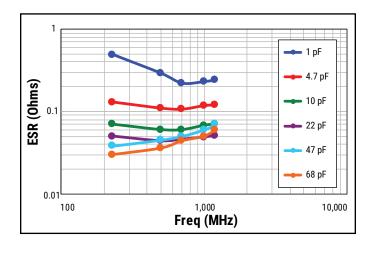
Rated Voltage (VDC)	250 V
DWV	200%

Electrical Characteristics

SRF (MHz) vs. Cap (pF)



ESR vs. Frequency 0505



Q vs. Frequency 0505

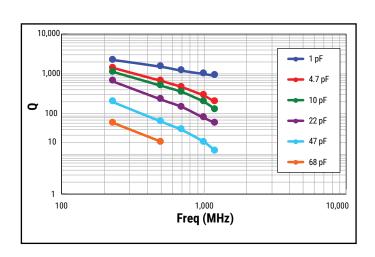




Table 1 - CBR Series, Capacitance Range Waterfall

0 0'		0505 (4444)
Case Size -	Inches (mm)	0505 (1414)
Length	mm (Inches)	1.40 +0.38 / -0.25 (0.055 +0.015 / -0.01)
Width	mm (lasks)	1.40 ± 0.38
Thiston	(Inches) mm	(0.055 ± 0.015) 1.15 ± 0.15
Thickness	(Inches)	(0.045 ± 0.006)
Bandwidth	mm (Inches)	0.25 + 0.25 - 0.13 (0.010 + 0.010 - 0.005)
Rated Volt	age (VDC)	250
Voltag	e Code	A
Capacitance	Capacitance Tolerance	Capacitance Code (Available Capacitance)
0.4 pF		408
0.5 pF 0.6 pF		508 608
0.7 pF		708
0.8 pF		808
0.9 pF		908
1.0 pF		109
1.1 pF 1.2 pF		119 129
1.3 pF		139
1.4 pF		149
1.5 pF		159
1.6 pF 1.7 pF		169
1.7 pF 1.8 pF		179 189
1.9 pF		199
2.0 pF		209
2.1 pF		219
2.2 pF		229
2.3 pF 2.4 pF		239
2.5 pF		259
2.6 pF	A = ±0.05pF B = ±0.10pF	269
2.7 pF	C = ±0.25pF	279
2.8 pF 2.9 pF	D = ±0.50pF	289
2.9 pF 3.0 pF		309
3.1 pF		319
3.2 pF		329
3.3 pF		339
3.4 pF		349 359
3.5 pF 3.6 pF		369
3.7 pF		379
3.8 pF		389
3.9 pF		399
4.0 pF		409
4.1 pF 4.2 pF		419 429
4.3 pF		439
4.4 pF		449
4.5 pF		459
4.6 pF 4.7 pF		469 479
4.7 pF 4.8 pF		489
4.9 pF		499
5.0 pF		509
Rated Volt	age (VDC)	250
Voltag	e Code	A

^{*} Available only in "B" (± 0.1 pF) capacitance tolerance.



Table 1 - CBR Series, Capacitance Range Waterfall cont'd

Case Size -	Inches (mm)	0505 (1414)
Length	mm (Inches)	1.40 +0.38 / -0.25 (0.055 +0.015 / -0.01)
Width	mm	1.40 ± 0.38
Width	(Inches)	(0.055 ± 0.015)
Thickness	mm (Inches)	1.15 ± 0.15 (0.045 ± 0.006)
Bandwidth	mm	0.25 + 0.25 - 0.13
	(Inches)	(0.010 + 0.010 - 0.005)
Rated Volt	age (VDC)	250
Voltag	e Code	A
Capacitance	Capacitance Tolerance	Capacitance Code (Available Capacitance)
5.1 pF		519
5.2 pF 5.3 pF		529 539
5.3 pF 5.4 pF		539
5.5 pF		559
5.6 pF		569
5.7 pF		579
5.8 pF		589
5.9 pF		599
6.0 pF		609
6.1 pF		619
6.2 pF		629
6.3 pF 6.4 pF		639
6.5 pF		659
6.6 pF		669
6.7 pF		679
6.8 pF		689
6.9 pF		699
7.0 pF		709
7.1 pF		719
7.2 pF	B = ±0.10pF	729
7.3 pF	C = ±0.25pF D = ±0.50pF	739
7.4 pF 7.5 pF	D - 10.30pr	749 759
7.6 pF		769
7.7 pF		779
7.8 pF		789
7.9 pF		799
8.0 pF		809
8.1 pF		819
8.2 pF		829
8.3 pF		839
8.4 pF 8.5 pF		849 859
8.6 pF		869
8.7 pF		879
8.8 pF		889
8.9 pF		899
9.0 pF		909
9.1 pF		919
9.2 pF		929
9.3 pF 9.4 pF		939
9.4 pF 9.5 pF		959
	age (VDC)	250
Voltag	e Code	Α Α



Table 1 - CBR Series, Capacitance Range Waterfall cont'd

Case Size -	Inches (mm)	0505 (1414)
Length	mm	1.40 +0.38 / -0.25
	(Inches) mm	(0.055 +0.015 / -0.01) 1.40 ± 0.38
Width	(Inches)	(0.055 ± 0.015)
TI: 1	mm	1.15 ± 0.15
Thickness	(Inches)	(0.045 ± 0.006)
Bandwidth	mm	0.25 + 0.25 - 0.13
	(Inches)	(0.010 + 0.010 - 0.005)
	tage (VDC)	250
Voltaç	je Code	A
Capacitance	Capacitance Tolerance	Capacitance Code (Available Capacitance)
9.6 pF		969
9.7 pF		979
9.8 pF		989
9.9 pF		999
10 pF		100
11 pF 12 pF	-	120
13 pF		130
15 pF		150
16 pF		160
18 pF		180
20 pF		200
22 pF		220
24 pF	F = ±1%	240
27 pF	G = ±2%	270
30 pF	J = ±5%	300
33 pF		330
36 pF		360
39 pF		390
43 pF		430
47 pF		470
51 pF		510
56 pF		560
62 pF		620
68 pF		680
75 pF		750
82 pF		820 910
91 pF 100 pF		101
	tage (VDC)	250
voltag	je Code	Α



Table 2 - Chip Thickness/Reeling Quantities

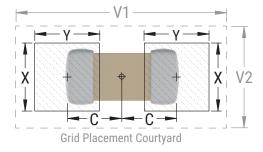
Chip Size	Chip Thickness	Reel Quantity		
Inches (mm)	(mm)	7" Paper	13" Paper	
0505 (1414)	1.15 ±0.15	3,000	Contact KEMET for availability.	

Table 3 – Chip Capacitor Land Pattern Design Recommendations per IPC-7351 (mm)

Case Size (Inches)	Case Size (mm)	Density Level A: Maximum (Most) Land Protrusion				Density Level B: Median (Nominal) Land Protrusion				Density Level C: Minimum (Least) Land Protrusion						
(IIICIICS)	(11111)	С	Y	X	V1	V2	С	Y	X	V1	V2	С	Y	X	V1	V2
0505	1414	0.92	1.15	1.89	3.99	2.89	0.82	0.95	1.79	3.09	2.29	0.72	0.75	1.69	2.43	1.93

Density Level A: For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of 0603(1608) and 0805 (2012) case sizes.

Density Level B: For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351). Image below based on Density Level B for an EIA 1608 case size.





Soldering Process

Recommended Soldering Technique:

• 0505 case sizes are limited to solder reflow only

Recommended Soldering Profile:

• KEMET recommends following the guidelines outlined in IPC/JEDEC J-STD-020

Recommended Solder Alloys:

Alloy	Composition	Solidus	Liquidous
In50	50 ln, 50 Pb	180°C	209°C
In52	52 ln, 48 Sn	118°C	118°C
Sn62	62.5 Sn, 36.1 Pb, 1.4 Ag	179°C	179°C
Sn63	63 Sn, 37 Pb	183°C	183°C
Pb-free	95.5 Sn, 3.8 Ag, 0.7 Cu	217°C	217°C
Hi-Temp	5 Sn, 93.5 Pb, 1.5 Ag	296°C	301°C
Sn5	5 Sn, 95 Pb	308°C	312°C



Table 4 – Performance & Reliability: Test Methods & Conditions

Stress		Test or Inspection M	ethod	Requirements
Terminal Strength	05	zing force: 05 case sizes: 5N e: 10±1 second		No visible damage or separation of termination system.
Vibration Resistance	Total am Test time	n frequency: 10 ~ 55 Hz/mini plitude: 1.5 mm e: 6 hours (Two hours each ir icular directions.)		No visible damage. Capacitance change and Q/DF: To meet initial specification
Solderability		emperature: 235±5°C time: 2±0.5 seconds		95% minimum coverage of termination finish.
Board Flex	means o deflection 5±1 seconstruction	or is mounted to a substrate of fram at a rate of 1 mm per son becomes 1 mm. (Deflection) room temperature for 24±2 hang electrical properties.	econd until the n is maintained for	No visible damage. Capacitance change: within ±5.0% or ±0.5 pF, whichever is larger. (Capacitance change is monitored during flexure.)
Resistance to Soldering Heat	Dipping Preheati the capa Store at	emperature: 260±5°C time: 10±1 second ng: 120 to 150°C for 1 minute citor in a eutectic solder. room temperature for 24±2 h ng electrical properties.		No visible damage. Capacitance change: within ±2.5% or ±0.25 pF, whichever is larger. Q/DF, IR and dielectric strength: To meet initial requirements. 25% maximum leaching on each edge.
	5 cycles	of steps 1 – 4:		
	Step	Temperature (°C)	Time (minutes)	
	1	Minimum operating temperatue +0/-3	30±3	No visible damage. Capacitance change: within ±2.5% or ±0.25 pF, whichever
Temperature Cycling	2	Room temperature	2 ~ 3	is larger.
,g	3	Maximum operating temperature +3/-0	30±3	Q/DF, IR and dielectric strength: To meet initial requirements.
	4	Room temperature (25°C)	2 ~ 3	
		room temperature for 24±2 h ng electrical properties.	nours before	



Table 4 - Performance & Reliability: Test Methods & Conditions (cont.)

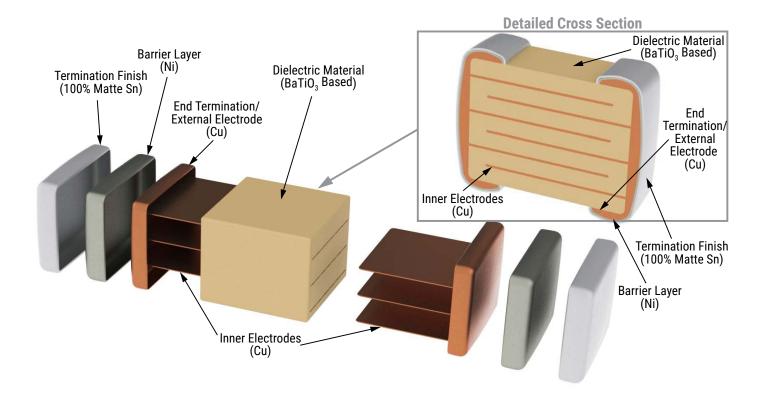
Stress	Test or Inspection Method	Requirements
Humidity (Damp Heat) Steady State	Test temperature: 40±2°C Humidity: 90 ~ 95% RH Test time: 500 +24/-0 hours Store at room temperature for 24±2 hours before measuring electrical properties.	No visible damage. Capacitance change: within $\pm 5.0\%$ or ± 0.5 pF, whichever is larger. Q/DF value: Capacitance ≥ 30 pF, Q ≥ 350 , $10 \text{ pF} \leq \text{Capacitance} < 30 \text{ pF}, \text{Q} \geq 275 + 2.5 ^{\circ}\text{C}$ Capacitance $< 10 \text{ pF}; \text{Q} \geq 200 + 10 ^{\circ}\text{C}$ IR: $\geq 16\Omega$
Humidity (Damp Heat) Load	Test temperature: 40±2°C Humidity: 90 ~ 95% RH Test time: 500 +24/-0 hours Applied voltage: rated voltage Store at room temperature for 24±2 hours before measuring electrical properties.	No visible damage. Capacitance change: within $\pm 7.5\%$ or ± 0.75 pF, whichever is larger. Q/DF value: Capacitance ≥ 30 pF, Q ≥ 200 , Capacitance < 30 pF, Q $\geq 100+10/3$ °C IR: $\geq 500M\Omega$
High Temperature Life	Test temperature: 125±3°C Applied voltage: 200% of rated voltage (6.3 VDC – 250 VDC) Test time: 1,000 +24/-0 hours Store at room temperature for 24±2 hours before measuring electrical properties.	No visible damage. Capacitance change: within $\pm 3.0\%$ or ± 0.3 pF, whichever is larger. Q/DF value: Capacitance ≥ 30 pF, Q ≥ 350 , $10 \text{ pF} \leq \text{Capacitance} < 30 \text{ pF, Q} \geq 275 \pm 2.5^{\circ}\text{C}$ Capacitance $< 10 \text{ pF, Q} \geq 200 \pm 10^{\circ}\text{C}$ IR: $\geq 1 \text{ G}\Omega$
ESR	The ESR should be measured at room temperature and tested at frequency 1±0.1 GHz.	0505 Case Size 0.4pF ≤Capacitance <1.0pF: < 1500mΩ 1.0pF ≤Capacitance <10pF: < 250mΩ 10pF ≤Capacitance ≤100pF: < 200mΩ



Storage and Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature –reels may soften or warp, and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C, and maximum storage humidity not exceed 70% relative humidity. In addition, temperature fluctuations should be minimized to avoid condensation on the parts, and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability, chip stock should be used promptly, preferably within 1.5 years of receipt.

Construction



Marking

Hi CBR series devices are supplied unmarked.

If you require marked product, please contact KEMET for availablility of a laser-marked option.



Tape & Reel Packaging Information

KEMET offers RF and Microwave Multilayer Ceramic Chip Capacitors packaged in 8 mm tape on 7" reels. This packaging system is compatible with all tape-fed automatic pick and place systems.

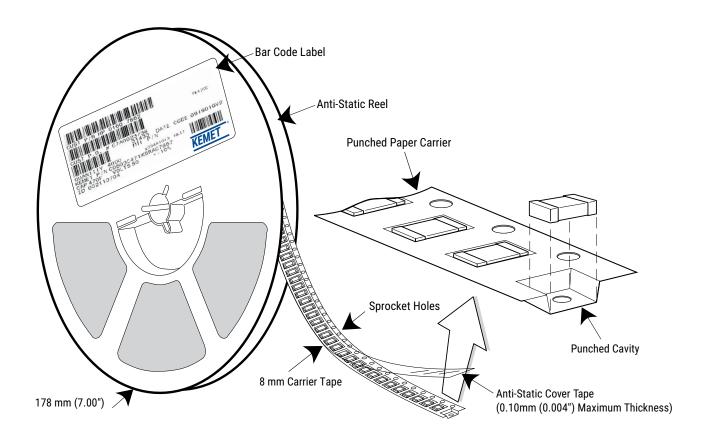


Table 5 – Carrier Tape Configuration (mm)

EIA Case Size	Tape Size (W)*	Pitch (P ₁)*	
0505	8	4	

^{*}Refer to Figure 1 & 2 for W and P1 carrier tape reference locations.

^{*}Refer to Table 6 for tolerance specifications.



Figure 1 - Punched (Paper) Carrier Tape Dimensions

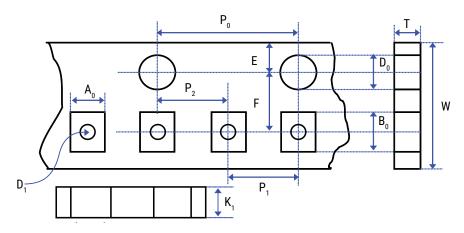


Table 6 - Punched (Paper) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)								
Tape Size	Do		E	P_0	P ₂	R Refere	nce Note 1	K_0
8 mm	1.55+ (0.061+		.75±0.10 069±0.004)	4.0±0.10 (0.157±0.004)	2.0±0.0 (0.079±0.0		25.0 .984)	Maximum 1.5 (Maximum 0.060)
Variable Dimensions — Millimeters (Inches)								
Tape Size	Pitch	A_0	B ₀	F	P ₁	Т	W	D ₁
8 mm	Single (4 mm)	Maximum 1.9 (Maximum 0.075)	Maximum 1.90 (Maximum 0.075)	3.5±0.05 (0.138±0.002)	4.0±0.1 (0.157±0.004)	0.23±0.1 (0.009±0.004)	8.0±0.2 (0.315±0.0	

^{1.} The tape with or without components shall pass around R without damage (see Figure 3).



Packaging Information Performance Notes

1. Cover Tape Break Force: 1.0 Kg minimum.

2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength	
8 mm	0.1 to 1.0 Newton (10 to 100 gf)	
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)	

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

3. Labeling: Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

Figure 2 – Bending Radius

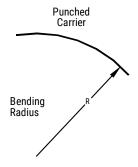


Figure 3 - Tape Leader & Trailer Dimensions

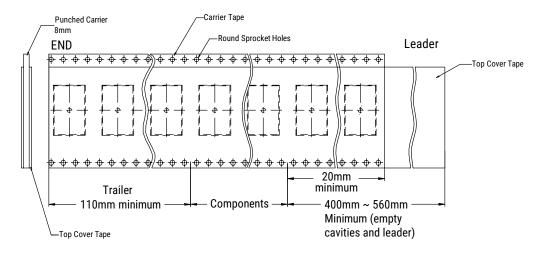




Figure 4 - Maximum Camber

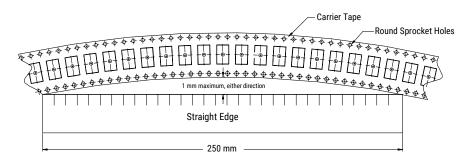


Figure 5 - Reel Dimensions

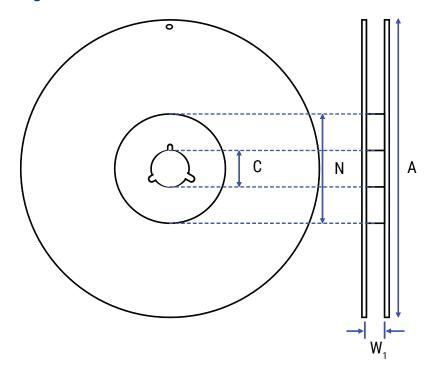


Table 7 - Reel Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)						
Tape Size	Reel Size	A	С			
8 mm	7	178±0.10 (7.008±0.004)	13.0±0.50 (0.512±0.02)			
Variable Dimensions — Millimeters (Inches)						
Tape Size	N Minimum See Note 2, Table 6	W ₁				
8 mm	60±1.0 (2.362±0.04)	8.4+1.5/-0.0 (0.331+0.059/-0.0)				



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1812J1K00473KXT 1812J2K00680JCT 1812J4K00102MXT 1812J5000102JCT 1812J5000103JCT 1812J5000682JCT NIN-FB391JTRF

NIN-FC2R7JTRF NPIS27H102MTRF C1206C101J1GAC C1608C0G1E472JT000N C2012C0G2A472J 2220J2K00101JCT

KHC201E225M76N0T00 LRC-LRF1206LF-01R025FTR1K 1812J1K00222JCT 1812J2K00102KXT 1812J2K00222KXT

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CGA2B2C0G1H040C CGA2B2C0G1H050C CGA2B2C0G1H060D CGA2B2C0G1H070D CGA2B2C0G1H151J CGA2B2C0G1H1R5C

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CGA3E1X7R1C474K